

General Description

The AAT7357 is a low threshold dual MOSFET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s ultra high density MOSFET process and space saving small outline Jlead package, performance superior to that normally found in a TSSOP-8 footprint has been squeezed into the footprint of a TSOPJW-8 package.

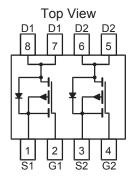
Features

- $V_{DS(MAX)} = -20V$ $I_{D(MAX)}^{1} = -5A @ 25^{\circ}C$
- Low R_{DS(ON)}:
 39 mΩ @ V_{GS} = -4.5V
 63 mΩ @ V_{GS} = -2.5V

Dual TSOPJW-8 Package

Applications

- **Battery Packs**
- Cellular & Cordless Telephones
- Battery-powered portable equipment



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V _{DS}	Drain-Source Voltage		-20	V	
V _{GS}	Gate-Source Voltage		±12		
I _D	Continuous Drain Current @ T _J =150°C ¹	T _A = 25°C	±5		
		T _A = 70°C	±4	Α	
I _{DM}	Pulsed Drain Current ²		±12		
I _S	Continuous Source Current (Source-Drain Diode) 1		-1.3		
P_{D}	Maximum Power Dissipation ¹	$T_A = 25^{\circ}C$	1.6	W	
		T _A = 70°C	1.0		
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C	

Thermal Characteristics

Symbol	Description	Тур	Max	Units	
$R_{\theta JA}$	Junction-to-Ambient steady state, one FET on ¹	115	140	°C/W	
$R_{\theta JA2}$	Junction-to-Ambient t<5 seconds 1	64	78	°C/W	
$R_{\theta JF}$	Junction-to-Foot ¹	60	72	°C/W	

1 7357.2003.08.0.6



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units	
DC Charac	DC Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V	
R _{DS(ON)}	Drain-Source ON-Resistance ²	V _{GS} =-4.5V, I _D =-5A		30	39	mΩ	
		V _{GS} =-2.5V, I _D =-4A		49	63	11122	
I _{D(ON)}	On-State Drain Current ²	V_{GS} =-4.5V, V_{DS} =-5V (Pulsed)	-12			Α	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=-250\mu A$	-0.6			V	
I _{GSS}	Gate-Body Leakage Current	V_{GS} =±12V, V_{DS} =0V			±100	nA	
I _{DSS}	Drain Source Leakage Current	V_{GS} =0V, V_{DS} =-20V			-1	μА	
		V_{GS} =0V, V_{DS} =-16V, T_J =70°C 3			-5		
g _{fs}	Forward Transconductance ²	V_{DS} =-5V, I_{D} =-5A		12		S	
Dynamic C	Dynamic Characteristics ³						
Q_{G}	Total Gate Charge	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V		14			
Q_{GS}	Gate-Source Charge	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V		3.5		nC	
Q_{GD}	Gate-Drain Charge	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V		5.6			
t _{D(ON)}	Turn-ON Delay	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V, R_{G} =6 Ω		TBD			
t _R	Turn-ON Rise Time	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V, R_{G} =6 Ω		TBD		ne	
t _{D(OFF)}	Turn-OFF Delay	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V, R_{G} =6 Ω		TBD		ns	
t _F	Turn-OFF Fall Time	V_{DS} =-10V, R_{D} =2.0 Ω , V_{GS} =-4.5V, R_{G} =6 Ω		TBD			
Source-Dr	Source-Drain Diode Characteristics						
V _{SD}	Source-Drain Forward Voltage ²	V _{GS} =0, I _S =-5A			-1.2	V	
Is	Continuous Diode Current ¹				-1.3	Α	

Notes:

2 7357.2003.08.0.6

^{1.} Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications. $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$ where the foot thermal reference is defined as the normal solder mounting surface of the device's leads. $R_{\theta JF}$ is guaranteed by design, however $R_{\theta CA}$ is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

^{2.} Pulse test: Pulse Width = 300 µs

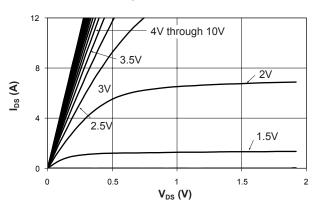
^{3.} Guaranteed by design. Not subject to production testing.



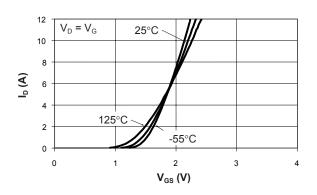
Typical Characteristics

(T_{.1} = 25°C unless otherwise noted)

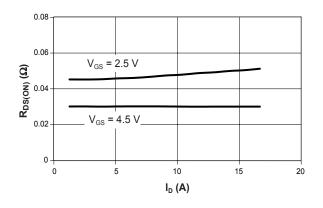
Output Characteristics



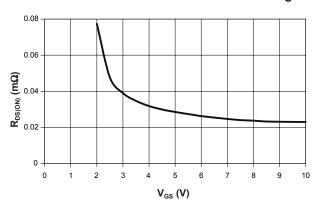
Transfer Characteristics



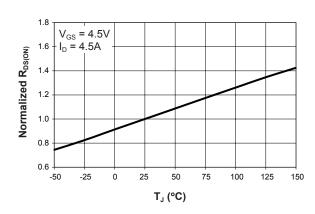
On-Resistance vs. Drain Current



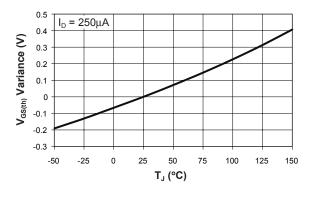
On-Resistance vs. Gate to Source Voltage



On-Resistance vs. Junction Temperature



Threshold Voltage



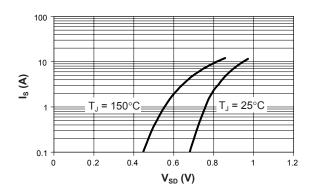
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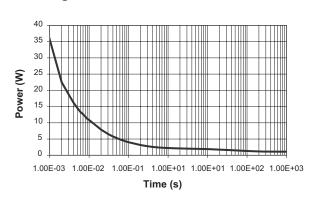
Typical Characteristics

 $\overline{(T_J = 25^{\circ}C \text{ unless otherwise noted})}$

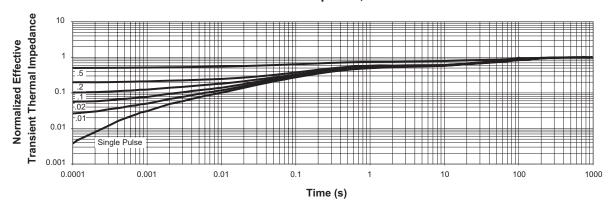
Source-Drain Diode Forward Voltage



Single Pulse Power, Junction to Ambient



Transient Thermal Response, Junction to Ambient



4 7357.2003.08.0.6

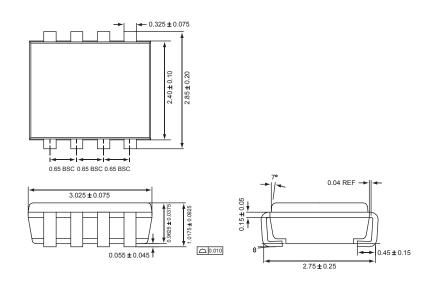


Ordering Information

Package	Marking	Part Number (Tape and Reel)
TSOPJW-8		AAT7357ITS-T1

Package Information

TSOPJW-8



All dimensions in millimeters.

7357.2003.08.0.6



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6 7357.2003.08.0.6